



2514
10/8/01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Perez, Erasmo; Roman, David T.
Assignee: Amkor Technology, Inc.
Title: Semiconductor Package With Exposed Die Pad And Body-Locking Leadframe
Serial No.: 09/436,158 Filing Date: November 9, 1999
Examiner: N. Ha Group Art Unit: 2814
Docket No.: M-7744 US

San Jose, California
October 8, 2001

COMMISSIONER FOR PATENTS
Washington, D.C. 20231

**INFORMATION DISCLOSURE STATEMENT
UNDER 37 CFR § 1.97(c) WITH FEE**

Dear Sir:

Pursuant to 37 C.F.R. § 1.56, § 1.97 and § 1.98, Applicants wish to call the documents listed on the accompanying PTO Form-1449 to the Examiner's attention. Copies of these documents are enclosed.

Citation of these documents shall not be construed as:

1. an admission that the documents are necessarily prior art with respect to the instant invention;
2. a representation that a search has been made, or
3. an admission that the information cited herein is, or is considered to be, material to patentability as defined in § 1.56(b).

LAW OFFICES OF
SKJERVEN MORRILL
MacPHERSON LLP

Statement fee under 37 C.F.R. § 1.17(p). The Commissioner is hereby authorized to charge

any additional fees which may be required, or credit any overpayment to Deposit Account

No. 19-2386. This paper is being submitted in duplicate.

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on October 8, 2001.

JEP

Attorney for Applicants

10/8/01
Date of Signature

Respectfully submitted,

JEP
James E. Parsons
Attorney for Applicants
Reg. No. 34,691

807007